

2

, , BGA, CSP

1 ,

2 ,

3 가 ,

4a 가 ,

4b ,

5 , (hole) 가 .

* *

10, 110: 11:

12: 20, 200:

30: (solder) 31, 131:

32: (bonding wire)

40a: 40b:

50: 51: (heater block)

60, 160: 60a:

60b: 63:

70a, 70b, 70c: (via hole)

80a, 180a: (solder bump) 80b: (solder ball)

81: (solder fillet) 82: (hole)

83a, 83c: 83b :

(flexible)

(solder bump)

(31) (10) 1 (11,12; substrate)
 1), (60a,60b), (31) (60a,60b) (100) (3
 e) (31) (11, 12) (10) (11, 12) (32; bonding wir (6
 0a) (60b) (70a; via hole) (80a) (11, 12)
 (20) (11, 12) (60a, 60b)
 (70a) (11) (60b) (12) (60a) (
 80a) (10) (11, 12) (60a) (6
 0a, 60b), (63) (60a, 60b) (70a)

(10) 2 3

가 가

가

가

가

가

가

(CSP; chip scale package)

가

(40a, 40b) (110) (40a, 40b)
 (30) (80b) (60) (40a, 40b) (83a, 83c)
 (40a) (83c) (200) (40b) (83a)
 40b) (83a, 83c) (200) (40a, 40b) (40a,
 (64) (83a, 83c) (70c) 5
 (40a, 40b) (110) (60)
 가 (82)

(110) (40a, 40b) (83a, 83c)
 2 4a (200) (30)
 (40a, 40b) (heater block; 51) 가 (40b) (f
 lux) (80b) (40a)
 가

4b (200) (solder filet; 81) (80b)

(CSP)

(57)

1.

가 ;

가

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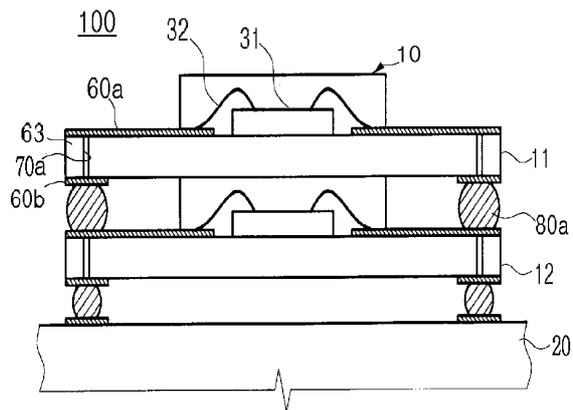
2.

1 ,

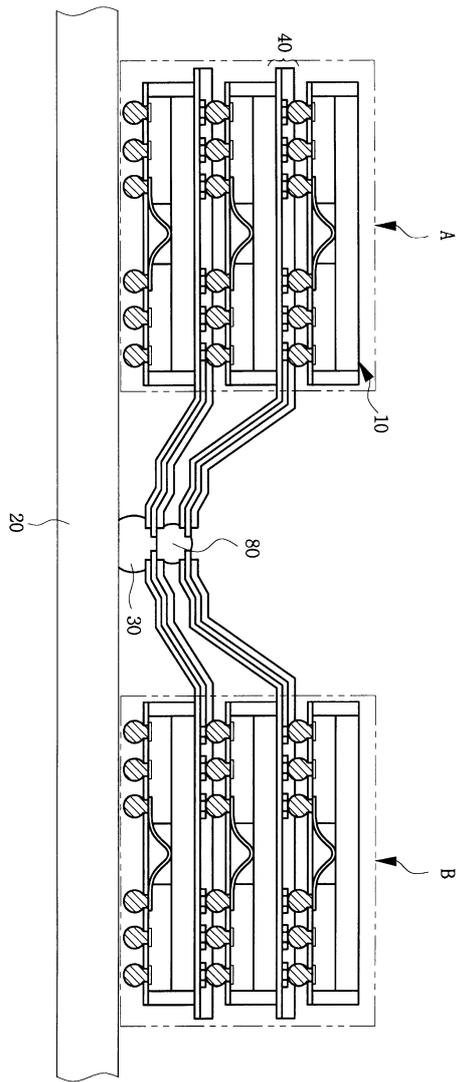
3.

1 , , ;
 ;
 ;
 4.
 3 , 가 ,
 5.
 3 , 가 가 ,
 , 가
 6.
 3 , ,

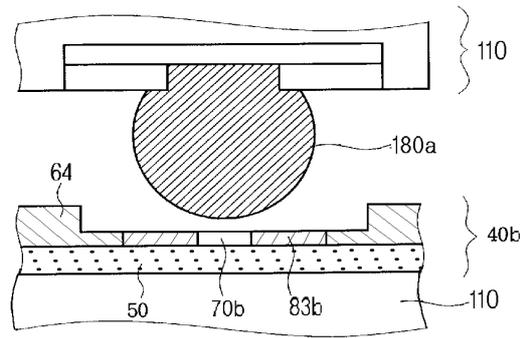
1



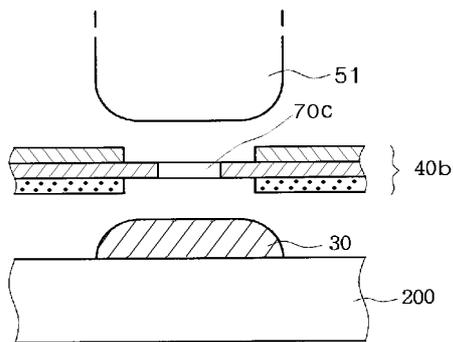
2



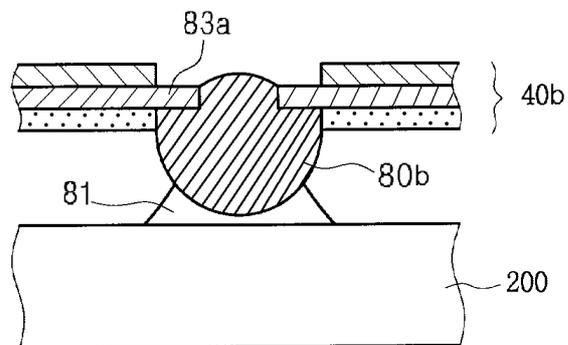
3



4a



4b



5

